

WHAT IS CLAIMED IS:

1. A CCD and CMOS image pickup module comprising a circuit main board on which an image sensor ( CMOS, CCD ) and relevant electronic elements are laid, a lens seat being disposed on an upper edge of a package of the image sensor, said image pickup module being characterized in that the lens seat has an image pickup cylinder correspondingly positioned above a coupling transistor of the image sensor, the image pickup cylinder at least covering an effective sensing area of the coupling transistor, the lens seat covering and enclosing the image sensor with the connecting section of the image pickup cylinder sealedly attaching to the periphery of the top face of the package of the image sensor, with the profile of the outer periphery of the package of the image sensor serving as a normal standard for the axis of the lens, the axis of the lens being projected onto the sensor center of the coupling transistor.
2. A CCD and CMOS image pickup module as claimed in claim 1, wherein the lens seat covers and encloses the image sensor ( CMOS, CCD ) to serve as a top package of the image sensor, the connecting section of the lens seat outward extending to encompass the outer periphery of the package of the image sensor, with the profile of the outer periphery of the package of the image sensor serving as a standard, the axis of the lens being projected onto the sensor center of the coupling transistor.
3. A CCD and CMOS image pickup module as claimed in claim 1,

wherein the top package of the image sensor ( CMOS, CCD ) includes a sealing glass sheet, an outer periphery of the glass sheet being overlaid on and flush with the profile of the package of the image sensor, an inner periphery of the bottom face of the connecting section of the lens seat being formed with a step face, an inner periphery of the step face having a dimension slightly smaller than that of the outer periphery of the glass sheet, the step face being attached to the periphery of the top face of the glass sheet, with the profile of the outer periphery of the package of the image sensor serving as a standard for the outer periphery of the step face, the axis of the lens being projected onto the sensor center of the coupling transistor.

4. A CCD and CMOS image pickup module as claimed in claim 1, wherein the top package of the image sensor ( CMOS, CCD ) includes a sealing glass sheet, an outer periphery of the glass sheet being slightly smaller than the profile of the package of the image sensor, an inner periphery of the bottom face of the connecting section of the lens seat being formed with a step face, an inner periphery of the step face having such a dimension as to encompass the entire glass sheet, with the profile of the outer periphery of the package of the image sensor serving as a standard for the outer periphery of the step face, the axis of the lens being projected onto the sensor center of the coupling transistor.
5. A CCD and CMOS image pickup module as claimed in claim 1, wherein the top package of the image sensor ( CMOS,

CCD )includes a sealing glass sheet, an outer periphery of the glass sheet being slightly smaller than the profile of the package of the image sensor, whereby a plane section free from covering of the glass sheet is left on the periphery of top face of the image sensor, an outer periphery of the lens seat having a dimension equal to that of the outer periphery of the image sensor, an inner periphery of the bottom face of the connecting section of the lens seat being formed with a stepped section having a first end face and a second end face, an inner periphery of the first end face having a dimension slightly larger than that of the outer periphery of the glass sheet, an inner periphery of the second end face having a dimension slightly smaller than that of the outer periphery of the glass sheet, the first and second end faces of the lens seat being respectively connected with the plane section of the periphery of top face of the image sensor and the top face of the glass sheet.